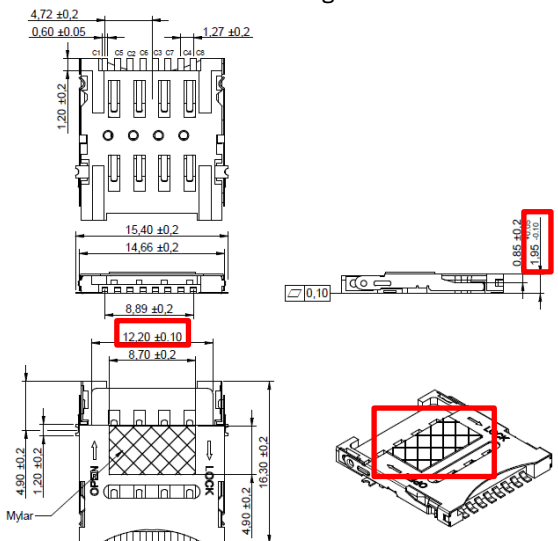
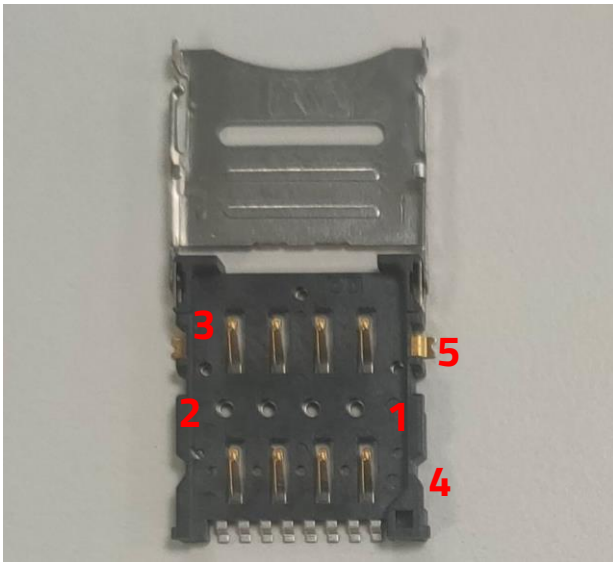
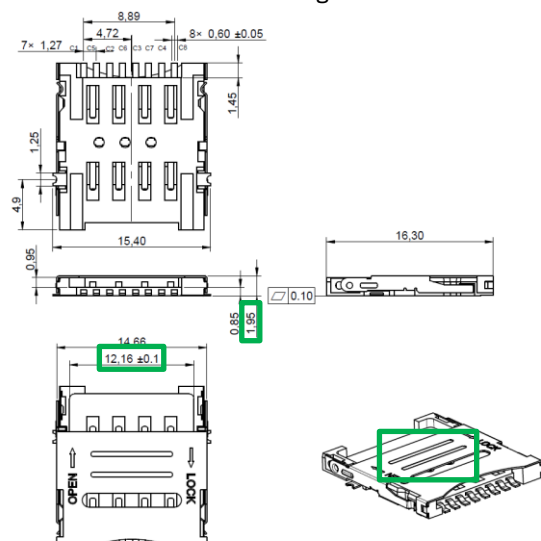
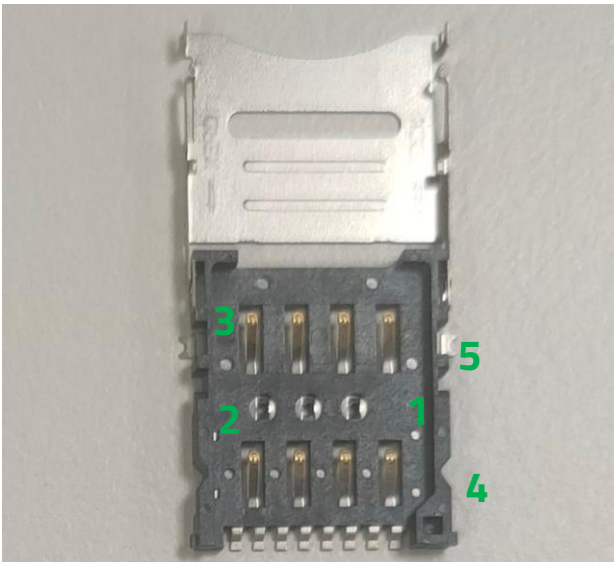
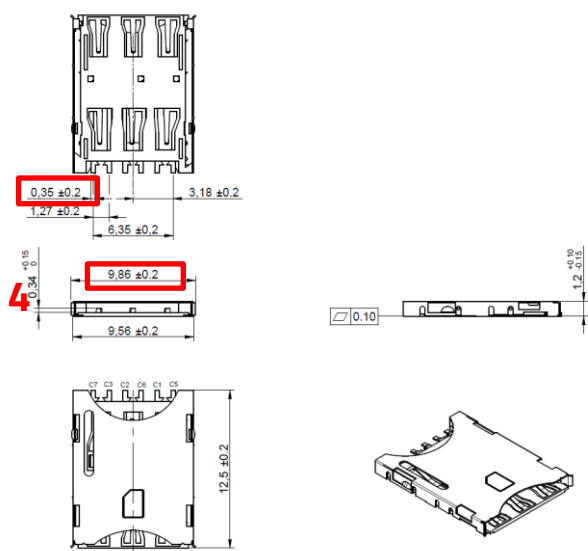
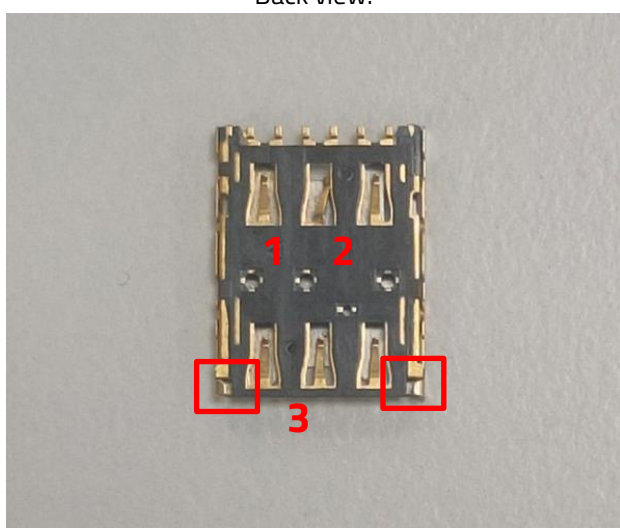
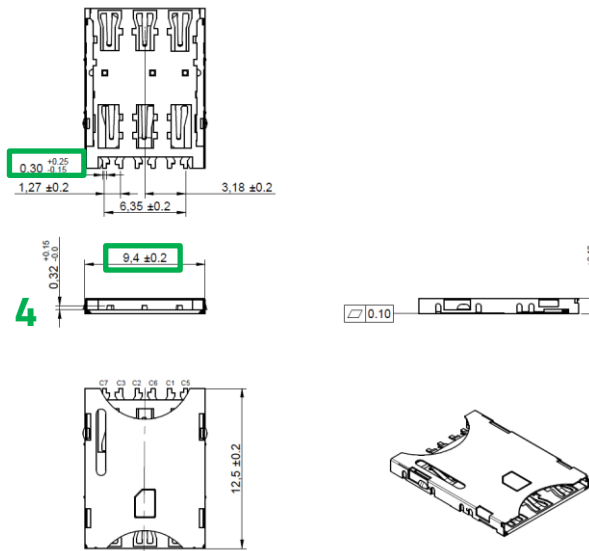
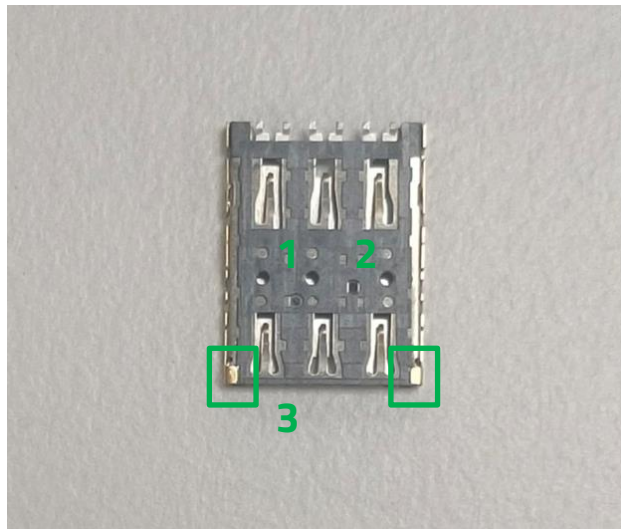




Product/Process Change Notice (PCN)	
<input checked="" type="checkbox"/> Major Change <input type="checkbox"/> Minor Change	
PCN Number: PCN_ConCARD_20250228 Affected Series: WR-CARD Affected Part Number: 693022010811 693043020611 PCN Date: 2024-11-28 Effective Date: 2025-02-28	Change Category: <input checked="" type="checkbox"/> Equipment/Location <input type="checkbox"/> General Data <input type="checkbox"/> Material <input type="checkbox"/> Process <input checked="" type="checkbox"/> Product Design <input type="checkbox"/> Shipping/Packaging <input type="checkbox"/> Supplier <input type="checkbox"/> Software
Contact: Product Management Phone: +49 (0) 7942 - 945 5001 Fax: +49 (0) 7942 - 945 5179 E-Mail: pcn.eican@we-online.com	Datasheet Change: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Attachment: <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No
DESCRIPTION OF CHANGE: <p>In order to enhance the product reliability, Würth Elektronik eiSos is switching to a fully automated production line. There will be no change in function of the product.</p> <p>The new revision of the affected order codes will be sent out after the previous revision is out of stock (according to FIFO - first-in, first-out). The new parts will have 586xxx lot numbers.</p>	
Details of Change: 693022010811: <ul style="list-style-type: none"> - Optimization of the insert molding design <ol style="list-style-type: none"> 1. Improvement of the stress release gaps for improved coplanarity 2. Reduction in size of the punch-removed sprues, widening of the release gaps 3. Thickening of the contact leads for improved mechanical performances 4. Increased crispness of the lock ears to release the stress and wear on the hinge rotation axis during locking/unlocking 5. Change of plating on the solder tabs to selective gold - Removal of the stamped WE logo - Removal of the mylar due to better hinge coplanarity and pick and place compatibility of the process 	

Before Change	After Change
<p style="text-align: center;">Drawing:</p>  <p style="text-align: center;">Open view:</p> 	<p style="text-align: center;">Drawing</p>  <p style="text-align: center;">Open view:</p> 
<p>693043020611:</p> <ul style="list-style-type: none"> - Optimization of the insert molding design <ol style="list-style-type: none"> 1. Improvement of the stress release gaps for improved coplanarity 2. Better precision of the punch-removed sprues, with regards to the release gaps 3. Selective plating of the insert molding: thicker gold on contact, nickel overall, tin on solder pins 4. Lower contact tilting to reduce wear on the SIM card - Straightening of the shielding 	

Before Change	After Change
<p style="color: red;">Drawing:</p>  <p style="color: red;">Back view:</p> 	<p style="color: green;">Drawing:</p>  <p style="color: green;">Back view:</p> 

Reliability / Qualification of Change:

An additional reliability testing was performed and approved:

- 693022010811: Qualification according to the "ConCRD MicroSIM Hinge Reliability Test Report".
- 693043020611: Qualification according to the "ConCRD NanoSIM Push-Pull Reliability Test Report".



An additional test sequence was made for qualification and can be found in the table below:

Test Item	Sample Size	Reference	Test Conditions	Acceptance
Wetting Balance 1	10	J-STD-002 G1	1.25 mm from contact pin and solder tab tip. Temperature: 245±5 °C Duration: 10 s max Speed: 16-25 mm/s	Approved
Salt Spray	10	EIA-364-26	Temperature: 35±2 °C Density: 5% in weight Duration: 48 hours	Approved
Wetting Balance 2	10	J-STD-002 G1	1.25 mm from contact pin and solder tab tip. Temperature: 245±5 °C Duration: 10 s max Speed: 16-25 mm/s	Approved